

# APPROVAL SHEET

**WW25MR025JTLJ**

**±5%**

Metal low ohm current sensing chip resistors

Size 2512 (6432) 1W

**(Automotive )**

\*Contents in this sheet are subject to change without prior notice.

## FEATURE

1. Metal low ohm and stable TCR performance
2. Automotive grade AEC Q-200 compliant
3. 100% CCD inspection
4. RoHS compliant and Lead free products

## APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

## DESCRIPTION

The resistors are constructed in a high grade low resistive metal body. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is Tin (lead-free) solder alloy.

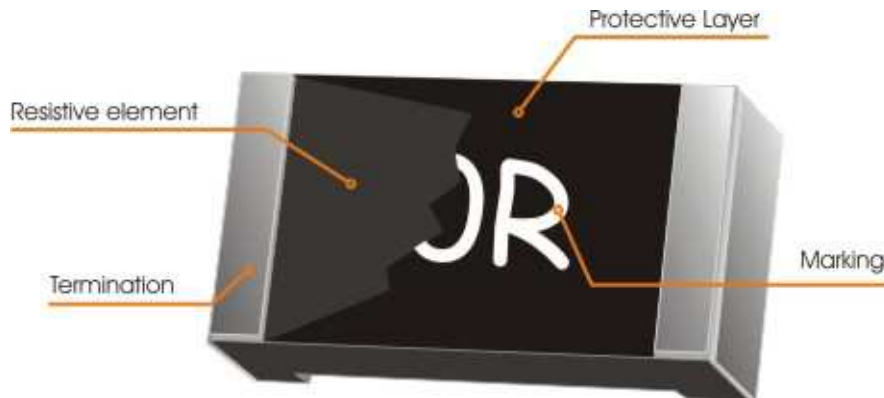
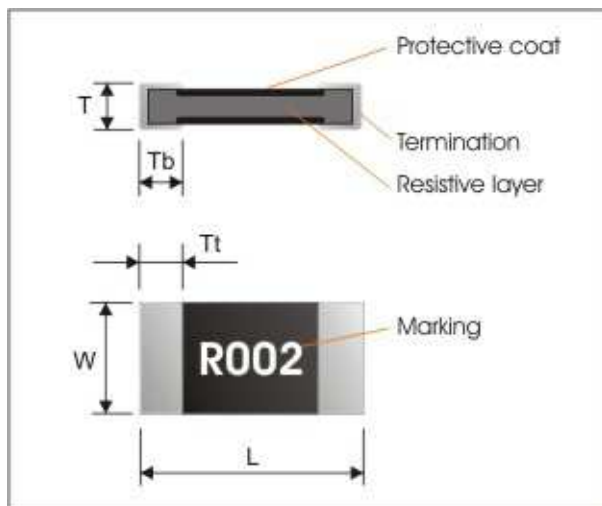


Fig 1. Construction of Chip-R

**QUICK REFERENCE DATA**

Item	General Specification
Series No.	WW25M
Size code	2512 ( 6432 )
Resistance Tolerance	±5%
Resistance Range	0.025Ω
TCR (ppm/°C)	≤ ±75 ppm/°C
Max. dissipation at T <sub>amb</sub> =70°C	1 W
Max. Operation Voltage (DC or RMS)	250V
Max. Overload Voltage (DC or RMS)	500V
Climatic category (IEC 60068)	55/155/56

**MECHANICAL DATA**

Symbol	Dimensions (mm)
L	6.20±0.20
W	3.20±0.20
T	0.60±0.20
Tt	0.80±0.20
Tb	0.80±0.20

**MARKING**

$$R025 = 0.025\Omega$$

**FUNCTIONAL DESCRIPTION****Derating curve**

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

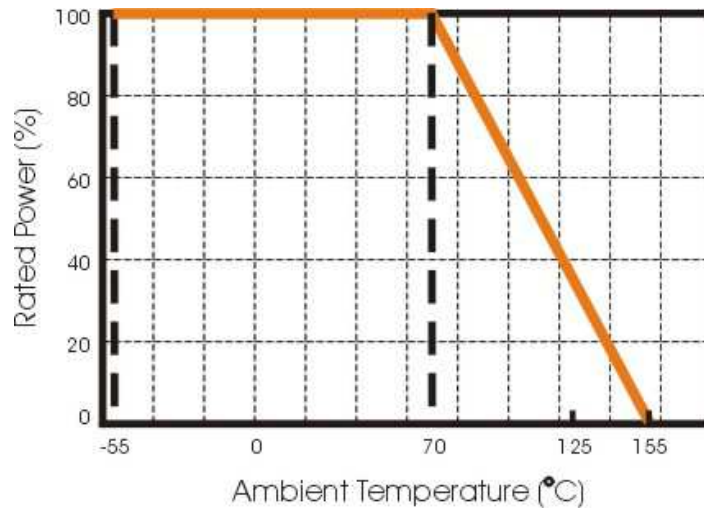


Fig.2 Maximum dissipation in percentage of rated power  
As a function of the ambient temperature

**MOUNTING**

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.

### SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

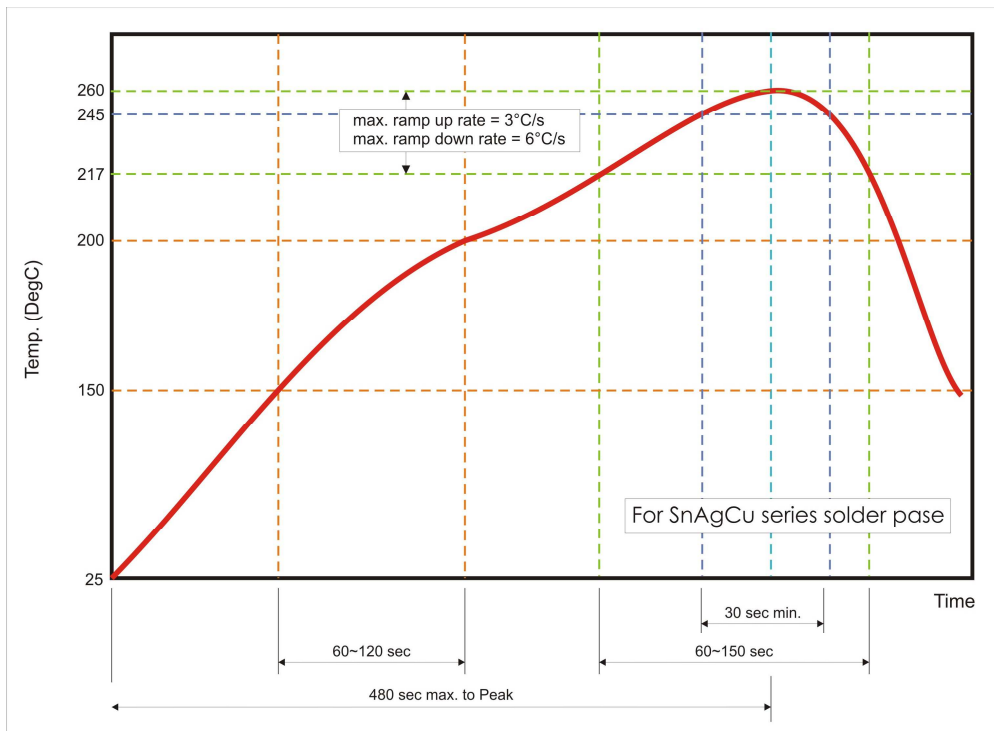


Fig 3. Infrared soldering profile for Chip Resistors WW25M

### CATALOGUE NUMBERS

The resistors have a catalogue number starting with

WW25	M	R025	J	T	L	J
<b>Size code</b> WW25 : 2512	<b>Type code</b> M : 1W Sensing type	<b>Resistance code</b> 0.025Ω = R025	<b>Tolerance</b> J : ±5%	<b>Packaging code</b> T : 7" reeled in tape	<b>Termination code</b> L = Sn base (lead free)	<b>Special code</b> J = Automotive grade AEC Q-200 compliant

Reeled tape packaging : 12mm width plastic emboss taping 4,000pcs per reel.

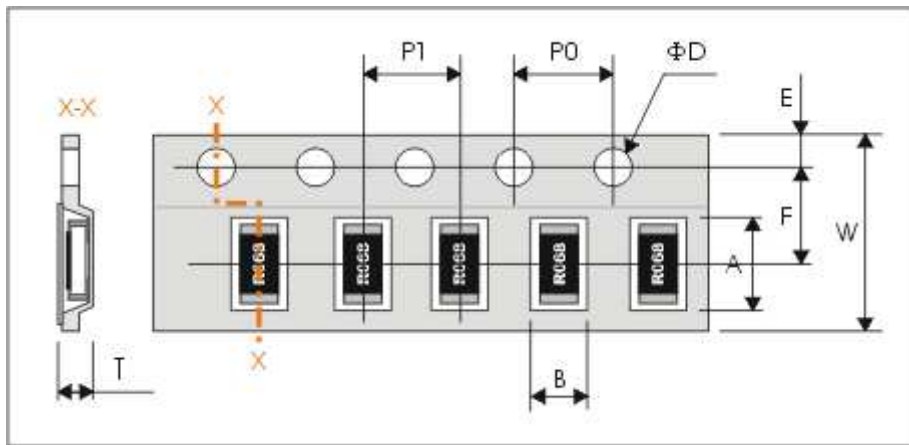
**TEST AND REQUIREMENTS ( AEC Q-200 )**

TEST	PROCEDURE / TEST METHOD	REQUIREMENT
		Resistor
Electrical Characteristics  <b>JISC5201-1: 1998</b> Clause 4.8	- DC resistance values measurement - Temperature Coefficient of Resistance (T.C.R) Natural resistance change per change in degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/}^\circ\text{C)}$ $t_1 : 20^\circ\text{C}+5^\circ\text{C}-1^\circ\text{C}$  $R_1$ : Resistance at reference temperature $R_2$ : Resistance at test temperature	Within the specified tolerance Refer to "QUICK REFERENCE DATA"
Resistance to soldering heat (R.S.H) <b>MIL-STD-202 method 210</b>	Un-mounted chips completely immersed for 10±1second in a SAC solder bath at 270°C ±5°C	ΔR/R max. ±(0.5%+0.005Ω) no visible damage
Solderability <b>J-STD-002</b>	a) Bake the sample for 155°C dwell time 4hrs/ solder dipping 235°C/ 5sec. b) Steam the sample dwell time 8 hour/ solder dipping 215°C/ 5sec. c) Steam the sample dwell time 8 hour/ solder dipping 260°C/ 7sec.	95% coverage min., good tinning and no visible damage
Temperature cycling <b>JESD22 Method JA-104</b>	1000 cycles, -55°C ~ +155°C, dwell time 30min maximum.	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
Moisture Resistance <b>MIL-STD-202 method 106</b>	65±2°C, 80~100% RH, 10 cycles, 24 hours/ cycle	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
Bias Humidity <b>MIL-STD-202 method 103</b>	1000+48/-0 hours; 85°C, 85% RH, 10% of operation power	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
Operational Life <b>MIL-STD-202 method 108</b>	1000+48/-0 hours; 35% of operation power, 125±2°C	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
High Temperature Exposure <b>MIL-STD-202 Method 108</b>	1000+48/-0 hours; without load in a temperature chamber controlled 155±3°C	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
Board Flex <b>AEC-Q200-005</b>	Resistors mounted on a 90mm glass epoxy resin PCB(FR4),bending once 2mm for 60sec.	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
Terminal strength <b>AEC-Q200-006</b>	Pressurizing force: 1.8Kg, Test time: 60±1sec.	No remarkable damage or removal of the terminations
Thermal shock <b>MIL-STD-202 method 107</b>	Test -55 to 155°C/ dwell time 15min/ Max transfer time 20sec 300cycles	ΔR/R max. ±(0.5%+0.005Ω) No visible damage
ESD <b>AEC-Q200-002</b>	Test contact 25KV (air).	ΔR/R max. ±(1%+0.005Ω) No visible damage

Mechanical Shock <b>MIL-STD-202</b> <b>method 213</b>	Test ½ Sine Pulse, Peak value: 100g, normal duration: 6ms, Velocity change:12.3ft/sec. Three shocks in each direction, total 18 shocks.	Within product specification tolerance and no visible damage.
Vibration <b>MIL-STD-202</b> <b>method 204</b>	Test 5g's for 20 min., 12 cycles each of 3 orientations.	△R/R max. ±(0.5%+0.005Ω) and no visible damage.
Resistance to Solvents : <b>MIL-STD-202</b> <b>Method 215</b>	Solvent is Isopropyl alcohol, immersion 3mins at 25°C and brush 10 strokes with a toothbrush with a handle made of a non-reactive material (wet bristle), immersion and brush 3 times and then air blow dry.	No superficial defect on marking, encapsulation, coating, appearance. Electrical characteristics within products specification and tolerance. Inspect at 3X max. for marking, inspect at 10X for part damage.
External Visual <b>MIL-STD-883</b> <b>method 2009</b>	Electrical test not required. Inspect device construction, marking and workmanship	No visual damage and refer WTC marking code.
Physical Dimension <b>JESD22</b> <b>method JB-100</b>	Verify physical dimensions(L, W, T, Tb, Tt)	Within the specified tolerance for WTC.

**PACKAGING**

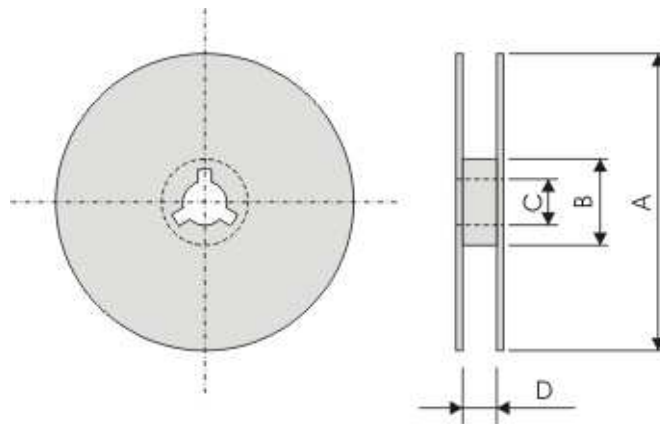
Plastic Tape specifications (unit :mm)



Symbol	A	B	W	F	E
Dimensions	6.75±0.20	3.50±0.20	12.00±0.30	5.50±0.1	1.75±0.10

Symbol	P1	P0	ΦD	T
Dimensions	4.00±0.10	4.00±0.10	Φ1.50 <sup>+0.1</sup> <sub>-0.0</sub>	Max. 1.2

**Reel dimensions**



Symbol	A	B	C	D
(unit : mm)	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	14.0±0.2

**Taping quantity**

- Chip resistors 4,000 pcs per reel.